Product Specification

108-60030

AMP Mini CT High Current Hybrid Drawer Connector 1.5 mm Pitch, Lead Free Version

1. Scope:

1.1 Contents:

This specification covers the requirements for product performance, test methods and quality assurance provisions of AMP Mini CT High Current Hybrid Drawer Connector, Lead Free Version. Applicable product description and part numbers are as shown in Fig.1.

Product Part No.	Description
x-292237-x	Plug Assembly, 1.5mm Pitch Mini CT High Current Hybrid Drawer Connector. (Lead Free)
x-292238-x	Receptacle Assembly, 1.5mm Pitch Mini CT High Current Hybrid Drawer Connector. (Lead Free)
x-179316-x	Receptacle Crimp Contact (#16-20) for Drawer Connector
x-179317-x	Receptacle Crimp Contact (#20-24) for Drawer Connector
x-316458-x	Receptacle GND Contact (#16-20) for Drawer Connector
x-179321-x	Plug Crimp Contact (#16-20) for Drawer Connector
x-179322-x	Plug Crimp Contact (#20-24) for Drawer Connector
84696-1	"S" Size Power Tab Dynamic Contact.
84695-1	"M" Size Power Receptacle Dynamic Contact.
179955-2	"S" Size Power Receptacle Dynamic Contact. (Strip)
179956-2	"M" Size Power Receptacle Dynamic Contact. Au 0.38µm (Strip)
179956-3	"M" Size Power Receptacle Dynamic Contact. Au 0.76µm (Strip)
316040-2	"S" Size Power Receptacle Dynamic Contact. (L/P)
316041-2	"M" Size Power Receptacle Dynamic Contact. (L/P)



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	LTR	REVISION RECORD	DR	DATE		1.5mm Pit	ch, Lead Free Versio	on		

2. Applicable Documents

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements this specification and referenced documents, this specification shall take precedence.

2.1 AMP Specifications:

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		ii)	Gold (over Palladiun	n-Nickel over Nickel und	erplating	
	Finish (Drawer	-	-	-	ickel underplating		
	Finish (Mini C	T post area): Ti	n plating o	ver Nickel un	derplating		
	Material:	Pł	osphor Bro	onze			
	A. Signal Contact						
3.2.1	Plug Assembly						
3.2	Materials:						
	product drawing.	the design, construct	ion and phy		one specifica on the appr	louoro	
5.1	-		ion and phy	sical dimensi	ons specified on the appl	icable	
3.1	Design and Constru	action:					
3.	Requirements:	nal Electrotechnical C	omission				
		Test Methods for El		d Electrical C	Component Parts.		
2.2		ards and Specification					
	C. 501-51024	Qualification Test	Report				
	B. 114-51009	Application Specif	ication				
	A. 109-5000	Test Specification,	General Ro	equirements fo	or Test Methods		

	B.	Power Contact					
		I) MIC (Multi-Interlock Connect	or) Co	ontact			
		Material:	Bras	s			
		Finish (Gold Version)	Gold	plating (mating area)		
			Tin J	olating (c	rimp area) over Nickel underplating		
		Finish (Tin Version)	Pre-j	plated Tin	1		
		II) Dynamic Contact					
		Material:	Cop	per Alloy			
		Finish:	Gold	plating (mating area) over Nickel underplating		
	C.	Housing					
		Material:	Glas	s-filled P	BT UL94V-0		
3.2.2	Red	ceptacle Assembly					
	A.	Signal Contact					
		Material:	Bras	s			
		Finish (Mini CT post area):	Tin J	olating ov	er Nickel underplating		
		Finish (Drawer mating area):	i)	Gold p	lating over Nickel underplating		
			ii)	Gold o	ver Palladium-Nickel over Nickel unde	rplating	
	В.	Power Contact					
		I) MIC					
		Material:	Phos	phor Bro	nze		
		Finish (Gold Version)	Gold	plating (mating area)		
			Tin J	plating (c	rimp area) over Nickel underplating		
		Finish (Tin Version)	Pre-j	plated Tin	1		
		II) Dynamic Contact					
		Material:	Cop	per Alloy			
		Finish:	Gold	plating (mating area) over Nickel underplating		
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Material: Glass-filled PBT UL94V-0

3.3 Ratings:

A.	Voltage Rating (Signal):	50 V(AC/DC)
	Voltage Rating (MIC):	250 VAC
	Voltage Rating (Dynamic):	630 VAC/DC
B.	Current Rating (Signal):	1A Max

Current Rating (MIC):

Wire Size			AWG		
wite Size	#16	#18	#20	#22	#24
Current	12 A	10 A	7 A	5 A	4 A

Current Rating (Dynamic)

Wire Size		AV	WG	
whe size	#10	#12	#14	#16
Current	30 A	25 A	19 A	16 A

C. Temperature Rating: -30 °C to +105 °C

The upper limit of the temperature includes the temperature rising resulted by the energized electrical current.

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3.4 Performance Requirements and Test Descriptions:

The product shall be designed to meet the electrical, mechanical and environmental performance requirements specified in Fig.2. All tests shall be performed in the room temperature unless otherwise specified.

3.5 Test Requirements and Procedures Summary:

Para.	Test Items	Requirements	Procedures
3.5.1	Examination of product	Product shall be confirming to the requirements of applicable product drawing and applicable Specification	Visually, dimensionally and functionally inspected per applicable quality inspection plan
		Electrical Requirements	·
3.5.2	Termination Resistance (Low Level)	Signal Line: $30 \text{ m}\Omega \text{ Max. (Initial)}$ $40 \text{ m}\Omega \text{ Max. (Final)}$ MIC Line: $6 \text{ m}\Omega \text{ Max. (Initial)}$ $10 \text{ m}\Omega \text{ Max. (Final)}$ Dynamic Line: $2 \text{ m}\Omega \text{ Max. (Initial & Final)}$	Signal/MIC Line: Subject mated connectors to 20 mV Max. open circuit at 10 mA Dynamic Line: Subject mated connectors to 50 mV Max. open circuit at 50 mA. Refer Fig. 4
3.5.3	Dielectric withstanding voltage	No creeping discharge or flashover shall occur. Current leakage: Signal Line: 5mA Max. MIC Line: 1 mA Max. Dynamic Line: 1 mA Max.	Signal Line: 500 VAC for 1 minute MIC Line: 1.8 kVAC for 1 minute Dynamic Line: 3 kVAC for 1 minute Test between adjacent circuits of mated connectors. MIL STD 202 TEST Method 301 IEC 512-2 TEST 4A

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Para.	Test items Requirements	Procedures			
3.5.4	Insulation Resistance	Signal/MIC Line: $500 \text{ M}\Omega \text{ Min. (Initial)}$ $100 \text{ M}\Omega \text{ Min. (Final)}$ Dynamic Line: $1000 \text{ M}\Omega \text{ Min.}$ $30^{\circ}\text{C} \text{ Max. under loaded rating}$			Impressed voltage 500VDC for 1 minute. Test between adjacent circuits of mated connectors. MIL STD 202 TEST Method 302 Condition A
3.5.5	Temperature Rising vs. Current	30°C M current	lax. under lo	aded rating	Contacts series-wired, apply test current of loaded rating current to the circuit, and measure the temperature rising by probing or soldered areas of contacts, after the temperature becomes stabilized deduct ambient temperature from the measured value. Refer Fig. 4
			Mechanic	al Requirer	ents
3.5.6	Crimp Tensile Strength (Power contacts only)		MIC Con re Size	Crimp Tensile	Apply an axial pull-off load to crimped wire, with the contact secured to the tester. Operation Speed: 100 mm/min
		$\frac{\text{mm}^2}{0.2}$	(AWG) #24 #22	N (kgf) M 19.6 (2.0 34.3 (3.1)
		0.5 0.85 1.25	#20 #18 #16	45.1 (4.0 98.0 (10. 186.2 (19))
		Dynamic Contacts			
		Wire Size Crimp Tensile		Crimp Tensile	
		$\frac{\text{mm}^2}{1.309}$ 2.081	(AWG) #16 #14	N (kgf) M 186.2 (1 245.0 (2)
		3.309 5.262	#12 #10	313.6 (3 401.8 (4)
3.5.7	Contact-housing Insertion Force (Power contacts only)	14.7 N	(1.5 kgf) Ma	ix. per conta	ct Measure force required to insert contact into housing.
3.5.8	Contact Retention Force	Tab: 7. Power (icle: 14.7N 84N (0.8kgf)	Measure contact retention force. Operation Speed: 100 mm/min.
			Fig. 2 (To l	be continue)
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Para.	Test Items	Requ	irements	Procedures						
3.5.9	Connector Mating Force	Pos. size	Initial &	Operation Speed: 100 mm/min						
		(Power/	After	Measure the force required to mate and	unmate					
		Signal)	Durability	connectors.						
			N (kgf) Min.							
		4/10	43.1 (4.4)							
		6/10	56.8 (5.8)							
		6/20	66.6 (6.8)							
3.5.10	Connector Unmating	Pos. size	Initial &	Operation Speed: 100 mm/min						
	Force	(Power/	After	Measure the force required to mate and unmate						
		Signal)	Durability	connectors.						
			N (kgf) Min. $7 \circ (0 \circ)$							
		4/10 6/10	7.8 (0.8)							
		6/10	10.8 (1.1) 11.8 (1.2)							
3.5.11	Durability (Repeated	Signal Line		Operation Speed: 100mm/min.						
5.5.11	Mate/Unmating)	$40 \text{ m}\Omega \text{ Ma}$		No. of Cycles:						
	maing)	MIC Line:		Gold Version: 1000cycles						
		$10 \text{ m}\Omega$ Ma		Pre-tin Version: 25 cycles.						
		Dynamic L								
		$2 \text{ m}\Omega \text{ Max}$								
3.5.12	Vibration	No electric		Subject mated connectors to 10-55-10 I	Hz travers	ed				
	(Low Frequency)		ity greater than	in 1 minute at 1.52mm amplitude 2 hours each of 3 mutually perpendicular planes.						
	(1μ sec. Sh								
		Signal Line		MIL-STD-202 TEST METHOD 201 CONDITION						
		40 mΩ Ma		Α						
		MIC Line:		IEC 68-2-6						
		10 mΩ Ma	x. (Final)	Mounting: Fig. 5						
		Dynamic L								
		2 mΩ Max	. (Final)							
3.5.13	Physical Shock	No electric	al	Accelerated Velocity: 490 mm/s ² (50G))					
			ity greater than							
		1 µ sec. Sh		Duration: 11 m sec						
		Signal Line		Number of shocks: 3 shocks in each direction						
		40 mΩ Ma		applied along the X, Y and Z axes, tota	lly 18					
		MIC Line:		shocks.						
		10 mΩ Ma		MIL-STD-202 TEST METHOD 213						
		Dynamic L		CONDITION A						
		2 mΩ Max	. (Final)	IEC 68-2-27, Test Ea Mounting: Fig. 5						
				Mounting: Fig. 5						
		J	Fig. 2 (To be co	ntinued)						
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			Fig. 2 (End)								
3.5.18	Temperat (Heat Agi		Signal Line: $40 \text{ m}\Omega \text{ Max. (Final)}$ MIC Line: $10 \text{ m}\Omega \text{ Max. (Final)}$ Dynamic Line: $2 \text{ m}\Omega \text{ Max. (Final)}$)]	Subject mated connector to 85±2°C, 500 MIL-STD-202 TEST Method 108.	0 hours.						
			40 m Ω Max. (Final) MIC Line: 10 m Ω Max. (Final) Dynamic Line: 2 m Ω Max. (Final)) (2 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	Subject mated connectors to 5±1% salt concentration for 48 hours. After test, rinse the samples with water and recondition the room temperature for 1 hour before subsequent measurements MIL-STD-202 TEST Method 101, Condition B. IEC 68-2-11, Test Ka.							
3.5.17	Cycling Salt Spra		$100 \text{ M}\Omega \text{ Min.}$ (Final Termination resistant Signal Line: $40 \text{ m}\Omega \text{ Max.}$ (Final) MIC Line: $10 \text{ m}\Omega \text{ Max.}$ (Final) Dynamic Line: $2 \text{ m}\Omega \text{ Max.}$ (Final)Signal Line:	nce 	10 cycles. Re-condition in room temperature for 3hrs subsequent measurement. MIL-STD-202 TEST Method 106 IEC 68-2-38, Test Db.							
 3.5.15 Thermal Shock 3.5.15 Thermal Shock 40 mΩ Max. (Final) MIC Line: 10 mΩ Max. (Final) Dynamic Line: 2 mΩ Max. (Final) 3.5.16 Humidity-Temperature 					Subject mated connectors to -55 °C/30min., +85 °C/30min. This being 1 cycle repeat for a total of 25 cycles. MIL-STD-202 TEST Method 107 Subject mated connector to 25-65°C, 90-95 %R.H.,							
			Dynamic Line: 2 mΩ Max. (Final) Environmenta	al Requir	ements							
		discontinuity greate 1 μ sec. Shall occur Signal Line: 40 mΩ Max. (Final) MIC Line: 10 mΩ Max. (Final)	. 1 ; ;	 hammering shocks in set up as shown in Fig. 6, with test current of 1 mA at DC 10 V applied to circuits as shown in Fig. 7 During the test, the circuit shall be monitored for fluctuation of electrical resistance. 								
Para.Test Items3.5.14Hammering Shocks			Requirements No electrical	:	Procedures Subject mated connectors to 10,000 cyc							

4. Product Qualification Test Sequence

	Test Group											
Test of Examination	1	2	3	4	5	6	7	8	9	10	11	12
	Test Sequence(a)											
Examination of Product	1,4,8	1, 3	1, 3	1, 3	1, 3	1,6	1,5	1, 5	1,5	1, 5	1,5	1, 5
Termination Resistance (Low Level)	2, 5					2, 5	2,4	2,4	2,4	2, 4	2,4	2,
Dielectric withstanding voltage	7											
Insulation Resistance	6											
Temperature Rising vs. Current		2										
Crimp Tensile Strength			2									
Contact-housing Insertion Force				2								
Contact Retention Force					2							
Connector Mating/Unmating Force (1th/25th cycle)						3						
Durability Cycling						4						
Vibration (Low Frequency)							3					
Physical Shock								3				
Hammering Shocks									3			
Thermal Shock										3		
Humidity-Temperature Cycling	3											
Salt Spray											3	
Temperature Life (Heat Aging)												3

Fig.3

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